

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3719	257/690	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 12:53
L2	2276	257/693	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 12:55
L3	1392	257/696	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 13:14
L4	3577	257/692	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 13:25
L5	282	257/694	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 13:40
L6	338	257/695	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 14:07
L7	5549	257/686	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 14:10
L8	4943	257/777	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 14:13

L9	7178	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 14:28
L10	1680	257/781	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 14:42
L11	3785	257/784	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 14:56
L12	1958	257/685	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/06 15:26
S1	6	"20020106833" or "6507106".pn. or "5646446".pn. or "5777391".pn. or "20020160598"	US-PGPUB; USPAT	OR	OFF	2008/01/10 19:09
S2	2344	257/777 and wire	USPAT	OR	OFF	2008/01/10 19:10
S3	2624	257/777 and wire	USPAT	OR	ON	2008/01/10 19:10
S4	1046	257/777 and wire and (chip or dice or die or IC or semiconductor) with opposit\$3	USPAT	OR	ON	2008/01/10 19:16
S5	86	(chip or dice or die or IC or semiconductor) with ("C" or "U") near shape with wir\$3	USPAT	OR	ON	2008/01/10 20:44
S6	7	("20010054762"   "5347159"   "5801439"   "6329708"   "6376769"   "6876074"   "6998704"). PN. OR ("7196418").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:26
S7	24	("3873173"   "4595794"   "4692790"   "4895523"   "5395253"   "5420461"   "5433631"   "5619067"). PN. OR ("6151220").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:29

S8	14	("3533023"   "3766439"   "3911234"   "4550357"   "4956695"   "5128744"   "5382829").PN. OR ("5534727").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:24
S9	24	("5714405"   "5805422"   "5895970"   "6002167"   "6165817").PN. OR ("6329708").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:33
S10	26	("4780098"   "5198888"   "5426072"   "5432378"   "5440452"   "5656856"   "5714405"   "5801439"   "5818107"   "5895970"   "5903437"   "5977640"   "6002167"   "6002177"   "6013948"   "6014316"   "6147398"   "6151220"   "6222212"   "6252300"   "6261136"   "6329708"   "6340845"   "6376769"   "6376904").PN. OR ("6984885").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:38
S11	29	("3294988"   "5714405"). PN. OR ("5895970").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:43
S12	9	("5081520"   "5224021"   "5397916"   "5413970"   "5663596"   "5801439"). PN. OR ("6147398").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:55
S13	18	("4433892").PN. OR ("4780098").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:02
S14	19	("20010015652"   "20010022396"   "5394303"   "5895970"   "6022759"   "6028365"   "6225688"   "6300679"   "6441476").PN. OR ("6646335").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:48
S15	91	("4721995"   "4783594"   "5072283"   "5220198"   "5285107"   "5332921"   "5347159"   "5363275"   "5382829"   "5397916"   "5408172"   "5448511"   "5534727"   "5567657"   "5646446"   "5659198"   "5661086"   "5684677"   "5708297"   "5763939"   "5767570"   "5776797"   "5789815"   "5805422"   "5831627"   "5886876"   "5925930"   "5980270"   "6002168"   "6002590"   "6014316").PN. OR	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:04

		("6300679").URPN.				
S16	22	("4635093"   "4682270"   "4691225"   "4864470"   "5281852"   "5311402"   "5703398"   "5747874"). PN. OR ("6022759").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 19:52
S17	49	("3417193"   "4266282"   "4365284"   "4426689"   "4473868"   "4568796"   "4586764"   "4673967"   "4701830"   "4722027"   "4785533"   "4801916"   "4870224"   "5041903"   "5043791").PN. OR ("5224021").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:02
S18	49	("3417193"   "4266282"   "4365284"   "4426689"   "4473868"   "4568796"   "4586764"   "4673967"   "4701830"   "4722027"   "4785533"   "4801916"   "4870224"   "5041903"   "5043791").PN. OR ("5224021").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:00
S19	7	("20010006252"   "20010040793"   "20030020153"   "20040104470"   "6300679"   "6323060"   "6351029").PN. OR ("7148087").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:16
S20	32	("3760090"   "3780352"   "3888639"   "4449769"   "4599636"   "4817280"   "4914259"   "4935584"   "5004639"   "5128831"   "5142448"   "5239448"   "5384691"   "5448511"   "5508565"   "5604379"   "5637828"   "5776797"   "5789815"   "5793108"   "5804874"   "5977640"   "6014316"   "6084294"   "6118176"   "6121676"   "6208521"   "6225688"   "6252176"   "6300679"). PN. OR ("6977441").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:17

S21	132	("20020006032"   "20020101261"   "20020139577"   "20020164838"   "20020180022"   "3436604"   "3654394"   "3727064"   "3746934"   "3772776"   "4103318"   "4288841"   "4398235"   "4406508"   "4437235"   "4513368"   "4645944"   "4696525"   "4733461"   "4763188"   "4821007"   "4823234"   "4833568"   "4862249"   "4884237"   "4891789"   "4911643"   "4953060"   "4956694"   "4983533"   "4985703"   "5012323"   "5016138"   "5034350"   "5041015"   "5099393"   "5104820"   "5138430"   "5159434"   "5198888"   "5222014"   "5224023"   "5239198"   "5241454"   "5247423"   "5259770"   "5261068"   "5262927"   "5279029"   "5281852"   "5289062"   "5311401"   "5313097"   "5343075"   "5347428"   "5375041"   "5377077"   "5394010"   "5402006"   "5420751"   "5428190"   "5446620"   "5455740"   "5475920"   "5479318"   "5484959"   "5493476"   "5499160"   "5514907"   "5523619"   "5541812"   "5543664"   "5561591"   "5566051"   "5572065"   "5592364"   "5612570"   "5631193"   "5644161"   "5654877"   "5776797"   "5778522"   "5801437"   "5805422"   "5828125"   "5835988"   "5869353"   "5926369"   "5949657"   "5953215"   "6014316"   "6025642"   "6028352"   "6028365"   "6072233"   "6097087"   "6172874"   "6205654"   "6208521"   "6225688"   "6233650"   "6262476"   "6262895"   "6265660"   "6266252"   "6281577"   "6300679"   "6323060"   "6351029"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:19
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		"6368896"   "6392162"   "6410857"   "6426240"   "6426549"   "6433418"   "6444921"   "6446158"   "6462412"   "6465877"   "6465893"   "6473308"   "6486544"   "6514793"). PN. OR ("6560117"   "6572387"   "6590282"   "6600222"   "6620651"   "6657134"   "RE36916"). PN. OR ("6940729").URPN.				
S22	49	("5159535"   "5450283"   "5578525"   "5646446"   "5773882"   "5783870"   "5949142"   "5969426"   "6071755"   "6075287"   "6208521"   "6324067"). PN. OR ("6486544").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:35
S23	10	("20040021139"   "5646446"   "6028365"   "6225688"   "6329712"   "6486544"   "6576992"   "6633078").PN. OR ("6924551").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:42
S24	3703	(chip or dice or die or IC or semiconductor) with ("C" or "U") with wir\$3	USPAT	OR	ON	2008/01/10 20:43
S25	199	(chip or dice or die or IC or semiconductor) with ("C" or "U") with shape with wir\$3	USPAT	OR	ON	2008/01/12 20:41
S26	113	S25 not S5	USPAT	OR	ON	2008/01/10 20:44
S27	50	(chip or dice or die or IC or semiconductor) with ("C" or "U") near shape with lead	USPAT	OR	ON	2008/01/10 20:49
S28	14	("4677458"   "5177326"   "5317479"   "5347159"   "5536909"   "5568363"   "5731631"   "5789804"   "5789809").PN. OR ("6087716").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 20:47
S29	614	(chip or dice or die or IC or semiconductor) and ("C" or "U") near shape with wir\$3	USPAT	OR	ON	2008/01/10 20:50
S30	521	S29 not S25	USPAT	OR	ON	2008/01/10 20:50

S31	15	("3349481"   "4794092"   "5311401"   "5347159"   "5808872"   "5818107"   "5918113"   "5925928"   "6180435"   "6198165"   "6268648"   "6284067"). PN. OR ("6346432").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/12 18:40
S32	9	("4491377"   "4618199"   "4869674"   "5108302"   "5772451"   "6016254"   "6124720"   "6229209"   "6232149").PN. OR ("6367763").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/10 21:28
S33	5339	257/666	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 18:42
S34	3291	257/690	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 20:21
S35	2	"6576992".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 19:05
S36	2	"20030081392"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 19:05
S37	3329	257/692	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 20:50
S38	340	(chip or dice or die or IC or semiconductor) and (interposer or interconnect \$3 or redistribut\$3) and ("C" or "U") with shape with wir\$3	USPAT	OR	ON	2008/01/12 20:50

S39	2084	257/693	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 21:15
S40	103	(chip or dice or die or IC or semiconductor) and (interposer or interconnect \$3 or redistribut\$3) same back near back	USPAT	OR	ON	2008/01/12 21:06
S41	171	(chip or dice or die or IC or semiconductor) and (board or carrier) same back near back	USPAT	OR	ON	2008/01/12 21:56
S42	329	(chip or dice or die or IC or semiconductor) and (substrate) same back near back	USPAT	OR	ON	2008/01/12 20:57
S43	75	("3539455"   "3542662"   "4180771"   "4252123"   "4365639"   "4431004"   "4474827"   "4484987"   "4592824"   "4608097"   "4627906"   "4636827"   "4660571"   "4671288"   "4703756"   "4759828"   "4781798"   "4836907"   "4869755"   "4877032"   "4890620"   "4935345"   "4969468"   "4975175"   "5007424"   "5016631"   "5067491"   "5165407"   "5174291"   "5186169"   "5190041"   "5207103"   "5215088"   "5314458"   "5318596"   "5322063"   "5324316"   "5325870"   "5330634"   "5358514"   "5388577"   "5403700"   "5441739"   "5463246"   "5470348"   "5476094"   "5497772"   "5508368"   "5514103"   "5527200"   "5571148"   "5571166"   "5582698"   "5593430"   "5603726"   "5651367"   "5660163"   "5693577"   "5694932"   "5707502"   "5711861"   "5727548"   "5750926"   "5755759"   "5791344"   "5928277"   "5951605"   "5965452"   "5972739"   "5999848"   "6041496"   "6119028"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/12 21:05

		"6259937").PN. OR ("7079881").URPN.				
S44	30026	(chip or dice or die or IC or semiconductor) and (interposer or interconnect \$3 or redistribut\$3) same wir\$3	USPAT	OR	ON	2008/01/12 21:07
S45	7005	(chip or dice or die or IC or semiconductor) and (interposer or interconnect \$3 or redistribut\$3) same wire near bond\$3	USPAT	OR	ON	2008/01/12 21:07
S46	2848	(chip or dice or die or IC or semiconductor) with (interposer or interconnect \$3 or redistribut\$3) with wire near bond\$3	USPAT	OR	ON	2008/01/12 21:07
S47	32	("3760090"   "3780352"   "3888639"   "4449769"   "4599636"   "4817280"   "4914259"   "4935584"   "5004639"   "5128831"   "5142448"   "5239448"   "5384691"   "5448511"   "5508565"   "5604379"   "5637828"   "5776797"   "5789815"   "5793108"   "5804874"   "5977640"   "6014316"   "6084294"   "6118176"   "6121676"   "6208521"   "6225688"   "6252176"   "6300679"). PN. OR ("6977441").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/12 21:13
S48	273	257/694	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 21:33
S49	17	("5072331"   "5140745"   "5239448"   "5258648"   "5598033"   "5677575"   "5776797"   "6157541"   "6225688").PN. OR ("6670700").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/12 21:18
S50	312	257/695	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 21:36

S51	1293	257/696	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 21:50
S52	4679	257/686	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 21:55
S53	4229	257/777	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 22:21
S54	2	257/777 and (chip or dice or die or IC or semiconductor) with (other or second or another) near (chip or dice or die or IC or semiconductor) with (distance or pitch) same (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 21:59
S55	0	stacked near (chip or dice or die or IC or semiconductor) with (other or second or another) near (chip or dice or die or IC or semiconductor) with (distance or pitch) same (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 21:59
S56	0	stacked near (chip or dice or die or IC or semiconductor) with (other or second or another) near (chip or dice or die or IC or semiconductor) with (distance or pitch) and (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 21:59

S57	0	stacked near (chip or dice or die or IC or semiconductor) with (other or adjacent or second or another) near (chip or dice or die or IC or semiconductor) with (distance or pitch) and (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 22:00
S58	16	stacked near (chip or dice or die or IC or semiconductor) with (distance or pitch) and (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 22:00
S59	1	array with stacked near (chip or dice or die or IC or semiconductor) with (distance or pitch) and (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 22:01
S60	0	multi\$3 with stacked near (chip or dice or die or IC or semiconductor) with (distance or pitch) and (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 22:01
S61	0	multi\$3 with stacked near (chip or dice or die or IC or semiconductor) same (distance or pitch) and (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 22:01
S62	5	multi\$3 with stacked near (chip or dice or die or IC or semiconductor) with (distance or pitch)	USPAT	OR	ON	2008/01/12 22:02
S63	7	module with stacked near (chip or dice or die or IC or semiconductor) with (distance or pitch)	USPAT	OR	ON	2008/01/12 22:05
S64	19	("5675180"   "5837566"   "5843807"   "5891761"   "6168973"   "6177296"). PN. OR ("6835598").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/01/12 22:04
S65	91	stacked near (chip or dice or die or IC or semiconductor) with (distance or pitch)	USPAT	OR	ON	2008/01/12 22:09

S66	6	array with stacked near (chip or dice or die or IC or semiconductor) with (distance or pitch)	USPAT	OR	ON	2008/01/12 22:10
S67	17	array with stacked near (chip or dice or die or IC or semiconductor) same (distance or pitch)	USPAT	OR	ON	2008/01/12 22:11
S68	0	stacked near (chip or dice or die or IC or semiconductor) with neighbor same (distance or pitch)	USPAT	OR	ON	2008/01/12 22:12
S69	0	stacked near (chip or dice or die or IC or semiconductor) same neighbor same (distance or pitch)	USPAT	OR	ON	2008/01/12 22:12
S70	319	(chip or dice or die or IC or semiconductor) same neighbor same (distance or pitch)	USPAT	OR	ON	2008/01/12 22:12
S71	9	(chip or dice or die or IC or semiconductor) same neighbor same (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 22:15
S72	481	(chip or dice or die or IC or semiconductor) with between with (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 22:16
S73	29	array with (chip or dice or die or IC or semiconductor) with between with (distance or pitch) with (microns or micrometers)	USPAT	OR	ON	2008/01/12 22:17
S74	99	array with (chip or dice or die or IC or semiconductor) with between with (distance or pitch) with (microns or micrometers or width)	USPAT	OR	ON	2008/01/12 22:20
S75	0	stacked with (chip or dice or die or IC or semiconductor) with (module or MOM) with (distance or pitch) with (microns or micrometers or width)	USPAT	OR	ON	2008/01/12 22:21

S76	113	stacked with (chip or dice or die or IC or semiconductor) with (module or MOM) and (distance or pitch) with (microns or micrometers or width)	USPAT	OR	ON	2008/01/12 22:30
S77	6396	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 22:34
S78	52	stacked with package with (module or MOM) and (distance or pitch) with (microns or micrometers or width)	USPAT	OR	ON	2008/01/12 22:30
S79	1521	257/781	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 23:18
S80	14	257/E31.117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 23:20
S81	4	257/E31.111	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 23:29
S82	12	257/E23.012	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/12 23:29

S83	28	( "20030062614"   "20040042190"   "4851613"   "5128831"   "5148266"   "5252857"   "5266912"   "5323060"   "5585675"   "5600183"   "5604377"   "5682061"   "5818107"   "5889652"   "5900738"   "5994166"   "6002590"   "6014320"   "6020749"   "6097611"   "6121676"   "6225688"   "6281577"   "6300679"   "6444921"   "6473308"   "6699730").PN. OR ("6982869").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 13:58
S84	32	( "3760090"   "3780352"   "3888639"   "4449769"   "4599636"   "4817280"   "4914259"   "4935584"   "5004639"   "5128831"   "5142448"   "5239448"   "5384691"   "5448511"   "5508565"   "5604379"   "5637828"   "5776797"   "5789815"   "5793108"   "5804874"   "5977640"   "6014316"   "6084294"   "6118176"   "6121676"   "6208521"   "6225688"   "6252176"   "6300679"). PN. OR ("6977441").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 13:59
S85	132	( "20020006032"   "20020101261"   "20020139577"   "20020164838"   "20020180022"   "3436604"   "3654394"   "3727064"   "3746934"   "3772776"   "4103318"   "4288841"   "4398235"   "4406508"   "4437235"   "4513368"   "4645944"   "4696525"   "4733461"   "4763188"   "4821007"   "4823234"   "4833568"   "4862249"   "4884237"   "4891789"   "4911643"   "4953060"   "4956694"   "4983533"   "4985703"   "5012323"   "5016138"   "5034350"   "5041015"   "5099393"   "5104820"   "5138430"   "5159434"   "5198888"   "5222014"   "5224023"   "5239198"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 13:59

		"5241454"   "5247423"   "5259770"   "5261068"   "5262927"   "5279029"   "5281852"   "5289062"   "5311401"   "5313097"   "5343075"   "5347428"   "5375041"   "5377077"   "5394010"   "5402006"   "5420751"   "5428190"   "5446620"   "5455740"   "5475920"   "5479318"   "5484959"   "5493476"   "5499160"   "5514907"   "5523619"   "5541812"   "5543664"   "5561591"   "5566051"   "5572065"   "5592364"   "5612570"   "5631193"   "5644161"   "5654877"   "5776797"   "5778522"   "5801437"   "5805422"   "5828125"   "5835988"   "5869353"   "5926369"   "5949657"   "5953215"   "6014316"   "6025642"   "6028352"   "6028365"   "6072233"   "6097087"   "6172874"   "6205654"   "6208521"   "6225688"   "6233650"   "6262476"   "6262895"   "6265660"   "6266252"   "6281577"   "6300679"   "6323060"   "6351029"   "6368896"   "6392162"   "6410857"   "6426240"   "6426549"   "6433418"   "6444921"   "6446158"   "6462412"   "6465877"   "6465893"   "6473308"   "6486544"   "6514793"). PN. OR ("6560117"   "6572387"   "6590282"   "6600222"   "6620651"   "6657134"   "RE36916"). PN. OR ("6940729").URPN.				
S86	55	("5159535"   "5450283"   "5578525"   "5646446"   "5773882"   "5783870"   "5949142"   "5969426"   "6071755"   "6075287"   "6208521"   "6324067"). PN. OR ("6486544").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 14:00
S87	7	("6147401"   "6486544"   "6576992"   "6727431"   "6765236"   "6765288"). PN. OR ("7071567").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 14:01

S88	11	("20020088987"   "20020134988"   "3283207"   "3508100"   "6396082").PN. OR ("6765236").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 14:08
S89	19	("6219074"   "6274890").PN. OR ("6396082").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 14:09
S90	246	(chip or dice or die or IC or semiconductor) with ("C" or "U") near shap\$3 with wir\$3	USPAT	OR	ON	2008/07/29 16:06
S91	7	("20010054762"   "5347159"   "5801439"   "6329708"   "6376769"   "6876074"   "6998704").PN. OR ("7196418").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 16:07
S92	24	("3873173"   "4595794"   "4692790"   "4895523"   "5395253"   "5420461"   "5433631"   "5619067").PN. OR ("6151220").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 16:10
S93	27	("5714405"   "5805422"   "5895970"   "6002167"   "6165817").PN. OR ("6329708").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 16:14
S94	33	("3294988"   "5714405").PN. OR ("5895970").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 16:22
S95	32	("4994411"   "5068712").PN. OR ("5714405").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 16:22
S96	3820	(chip or dice or die or IC or semiconductor) with ("C" or "U") with wir\$3	USPAT	OR	ON	2008/07/29 16:28
S97	110	stack\$3 with (chip or dice or die or IC or semiconductor) with ("C" or "U") with wir\$3	USPAT	OR	ON	2008/07/29 16:28
S98	108	S97 not S90	USPAT	OR	ON	2008/07/29 16:28
S99	13	("20030025211"   "20030111736"   "20030113998"   "20040238936"   "5384690"   "5620782"   "5933712"   "6180881"   "6236565"   "6426549"   "6514793"   "6576992"   "6627984").PN. OR ("7291907").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 16:30

S100	177	(interposer or transparent \$3 or translucent\$3 or glass) with (chip or dice or die or IC or semiconductor) with ("C" or "U") with wir\$3	USPAT	OR	ON	2008/07/29 16:36
S101	270	(interposer or transparent \$3 or translucent\$3 or glass) same (chip or dice or die or IC or semiconductor) with ("C" or "U") with wir\$3	USPAT	OR	ON	2008/07/29 16:44
S102	93	S101 not S100	USPAT	OR	ON	2008/07/29 16:45
S103	145	(interposer or transparent \$3 or translucent\$3 or glass) with (chip or dice or die or IC or semiconductor) with (around\$3 or surround\$3) with wir\$3	USPAT	OR	ON	2008/07/29 16:48
S104	368	(interposer or transparent \$3 or translucent\$3 or glass) with (chip or dice or die or IC or semiconductor) with cover \$3 with wir\$3	USPAT	OR	ON	2008/07/29 16:54
S105	28	("20020043706"   "20020089044"   "20020093078"   "5087964"   "5161009"   "5266828"   "5352852"   "5463229"   "5598033"   "5608262"   "5786589"   "5867368"   "6144507"   "6255769"   "6342406"   "6396043"   "6400075"   "6472761"   "6538322"   "6566745"   "6571466"   "6646335"   "6656768"   "6765288"   "6864116"   "6885107"   "6964886").PN. OR ("7122390").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 17:00
S106	10	("5729437"   "6384472"   "6455774"   "6476469"   "RE36614").PN. OR ("6649834").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 17:08
S107	45	("5729437").URPN.	USPAT	OR	OFF	2008/07/29 17:18

S108	864	(interposer or transparent \$3 or translucent\$3 or glass) with (substrate or lid or cap) and (substrate or cap or lid) with (chip or dice or die or IC or semiconductor) with cover \$3 with wir\$3	USPAT	OR	ON	2008/07/29 17:27
S109	157	(interposer or transparent \$3 or translucent\$3 or glass) with (substrate or lid or cap) and (substrate or cap or lid) with (chip or dice or die or IC or semiconductor) with cover \$3 with side with wir\$3	USPAT	OR	ON	2008/07/29 17:28
S110	14	("5397918"   "5650592"   "5753857"   "5773879"   "5804870"   "5877546"   "6057597"   "6130448"   "6204454"   "6232652"   "6294831"   "6313521"   "6317326"   "6531784"). PN. OR ("6967400").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 17:33
S111	46	(interposer or transparent \$3 or translucent\$3 or glass) with (substrate or lid or cap) and (substrate or cap or lid) with (chip or dice or die or IC or semiconductor) with cover \$3 with side with lead	USPAT	OR	ON	2008/07/29 17:40
S112	30	(interposer or transparent \$3 or translucent\$3 or glass) with (substrate or lid or cap) and (substrate or cap or lid) with (chip or dice or die or IC or semiconductor) with (around\$3 or surround\$3) with side with lead	USPAT	OR	ON	2008/07/29 17:42
S113	30	(interposer or transparent \$3 or translucen\$3 or glass) with (substrate or lid or cap) and (substrate or cap or lid) with (chip or dice or die or IC or semiconductor) with (around\$3 or surround\$3) with side with lead	USPAT	OR	ON	2008/07/29 17:44

S114	41	(interposer or transparent \$3 or transluce\$3 or glass) with (substrate or lid or cap) and (substrate or cap or lid) with (chip or dice or die or IC or semiconductor) with (around\$3 or surround\$3) with side\$7 with wire	USPAT	OR	ON	2008/07/29 17:44
S115	71	(interposer or transparent \$3 or transluce\$3 or glass) with (substrate or lid or cap) and (substrate or cap or lid) with (chip or dice or die or IC or semiconductor) with (cover \$3) with side\$7 with wire	USPAT	OR	ON	2008/07/29 17:47
S116	1156	(interposer or transparent \$3 or transluce\$3 or glass) with (substrate or lid or cap) and (substrate or cap or lid) with (chip or dice or die or IC or semiconductor) with (cover \$3) with side\$7	USPAT	OR	ON	2008/07/29 17:50
S117	7	("20040018662"   "5729038"   "6472247"   "6498115").PN. OR ("6873034").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 20:59
S118	12	("20020030261"   "5523608"   "6072233"   "6077724"   "6118176"   "6118184"   "6133067"   "6201302"   "6268648"   "6297547"   "6414381"   "6459039").PN. OR ("7211883").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 21:00
S119	56	("4663833"   "4894707"   "5079190"   "5220198").PN. OR ("5523608").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/29 21:00
S120	2	("2002/0088987").URPN.	USPAT	OR	OFF	2008/07/29 21:12
S121	1	"20070111567"	US-PGPUB; USPAT	OR	OFF	2008/07/29 21:14
S122	102	257/E21.511	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:16

S123	26	257/E21.519	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:21
S124	11	257/E23.133	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:21
S125	40	257/E27.15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:22
S126	2979	439/108	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:23
S127	37	257/E31.117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:26
S128	4	257/E31.111	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:27
S129	18	257/E23.012	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:27
S130	3579	257/784	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:29

S131	5582	257/666	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:48
S132	3491	257/690	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 21:50
S133	2161	257/693	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 22:19
S134	1340	257/696	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 22:39
S135	3439	257/692	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 22:47
S136	277	257/694	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 22:55
S137	319	257/695	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 22:57
S138	5108	257/686	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 23:00

S139	6755	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 23:01
S140	1590	257/781	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 23:03
S141	4523	257/777	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/29 23:06
S142	38	257/E31.117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 14:48
S143	5	257/E31.111	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 14:48
S144	18	257/E23.012	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 14:49
S145	5598	257/666	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 14:49
S146	3507	257/690	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 14:56

S147	3442	257/692	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 15:30
S148	2162	257/693	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 16:55
S149	2	"4743868".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 17:06
S150	277	257/694	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 19:26
S151	320	257/695	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 20:15
S152	1341	257/696	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/11 20:17
S153	0	(chip) and wire with coat \$3 same improv\$3	USPAT	OR	OFF	2008/08/11 20:19
S154	0	(chip or die) and wire with coat\$3 same improv\$3	USPAT	OR	OFF	2008/08/11 20:19
S155	699	(chip or die) and wire with coat\$3 same improv\$3	USPAT	OR	OFF	2008/08/11 20:19
S156	170	(chip) and wire with coat \$3 same improv\$3	USPAT	OR	OFF	2008/08/11 20:19
S157	153	radiation near detector with module	USPAT	OR	OFF	2008/08/11 20:30
S158	15	photon near detector with module	USPAT	OR	OFF	2008/08/11 20:34
S159	221	radiation near detector with module	USPAT	OR	ON	2008/08/11 20:38

S160	219	S159 not S158	USPAT	OR	ON	2008/08/11 20:38
S161	68	S159 not S157	USPAT	OR	ON	2008/08/11 20:38
S162	351	radiation near detector same module	USPAT	OR	ON	2008/08/11 20:48
S163	130	S162 not S159	USPAT	OR	ON	2008/08/11 20:48
S164	65	257/E31.117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:25
S165	9	257/E31.111	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:26
S166	34	257/E23.012	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:26
S167	178	257/E21.511	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:27
S168	37	257/E21.519	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:27
S169	21	257/E23.133	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:29
S170	58	257/E27.15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:29

S171	4501	438/108	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:30
S172	2506	438/109	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:33
S173	5894	257/666	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/02 18:54

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